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可靠性试验

Reliability Test Items And Conditions

Test Parameter	Reference Criterion	Test Condition	Time	Quantity	/ Ac/Re
Resistance to Soldering Heat	JESD22-B106	Temp:260 max T=6sec	2 times	22Pcs	0/1
thermocycling	JESD22-A104	120 ±5 30min. -40 ±5 30min.	100 Cycles	22Pcs	0/1
High Temperature storage	JESD22-A103	Temp:85 ±5	1000Hrs	22Pcs	0/1
Low Temperature storage	JESD22-A119	Temp:-40 ±5	1000Hrs	22Pcs	0/1
Operating Life Test	JESD22-A108	Ta=25 ±5 IF=30mA	1000Hrs	22Pcs	0/1
High Temperature High Humidity	JESD22-A101	85 ±5 /85 RH IF=30mA	1000Hrs	22Pcs	0/1

失效判断标准

Parameter	Symbol	Test Condition	Judgement standard	
			Min	Max

E=

使用注意事项（2）

Precautions (2)

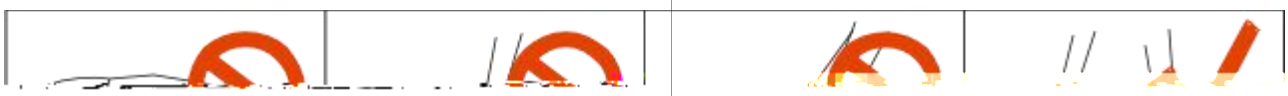
设计建议

使用注意事项（3）

Precautions (3)

其他事项

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED